

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/21/12916	
<b>1.3 Title of PCN</b>	ASE Kaohsiung (Taiwan) xFBGA package Bonding Wire procurement flexibility - On listed products	
<b>1.4 Product Category</b>	STM32Fx, STM32Gx, STM32Hx, STM32Lx, STM32MPx, STM32Ux, STM32Wx	
<b>1.5 Issue date</b>	2021-12-13	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	SAWTELLE KRISTIN
<b>2.1.2 Phone</b>	
<b>2.1.3 Email</b>	kristin.sawtelle@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Ricardo Antonio DE SA EARP
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	ASE Kaohsiung (Taiwan)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	ASE Kaohsiung back-end: - Gold wire bonding assembly line	ASE Kaohsiung back-end : - Gold wire bonding assembly line - New Copper Palladium added assembly line
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	no impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Due to the success on the market of STM MCU devices, ST Microcontrollers Division decided to qualify an additional back-end line to maintain state of the art service level to our customers thanks to extra capacity.
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	traceability ensured by ST internal tools
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2021-12-31
<b>7.2 Intended start of delivery</b>	2022-03-31
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	12916 MDG-MCD-RER2021 - ASE Kaohsiung (Taiwan) xFBGA Qual plan.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2021-12-13

**9. Attachments (additional documentations)**

12916 Public product.pdf  
12916 MDG-MCD-RER2021 - ASE Kaohsiung (Taiwan) xFBGA Qual plan.pdf  
12916 PCN12916\_Additional information.pdf

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F217IGH6	
	STM32F407IGH6	

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